## PACKAGE OF A SEMICONDUCTOR DEVICE WITH A FLEXIBLE WIRING SUBSTRATE AND METHOD FOR THE SAME

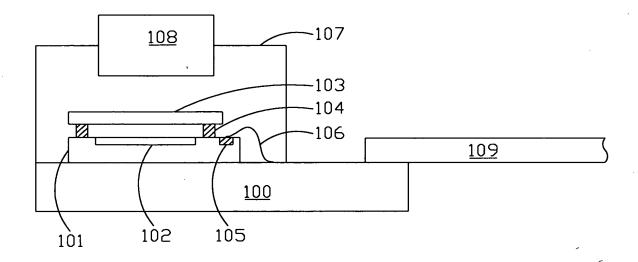
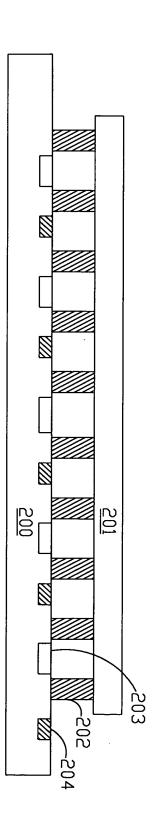


FIG.1(Prior Art)





## PACKAGE OF A SEMICONDUCTOR DEVICE WITH A FLEXIBLE WIRING SUBSTRATE AND METHOD FOR THE SAME

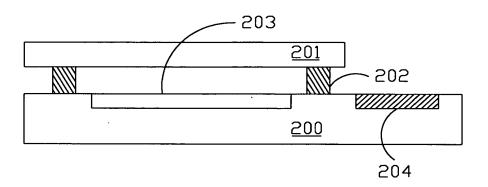


FIG.3

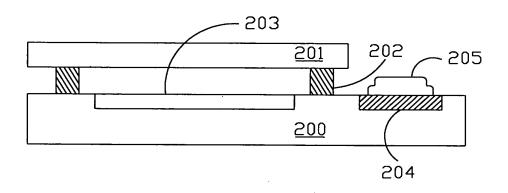


FIG.4

## PACKAGE OF A SEMICONDUCTOR DEVICE WITH A FLEXIBLE WIRING SUBSTRATE $\dot{}$ AND METHOD FOR THE SAME

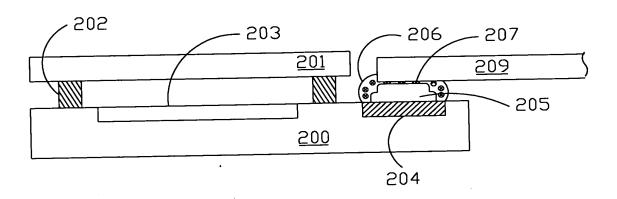


FIG.5

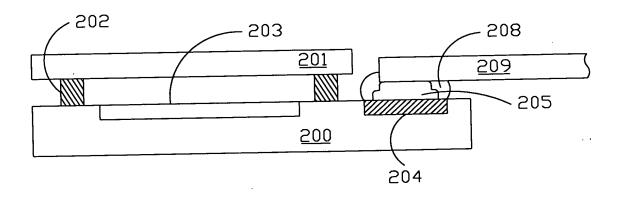


FIG.6

